

FIG. 1A

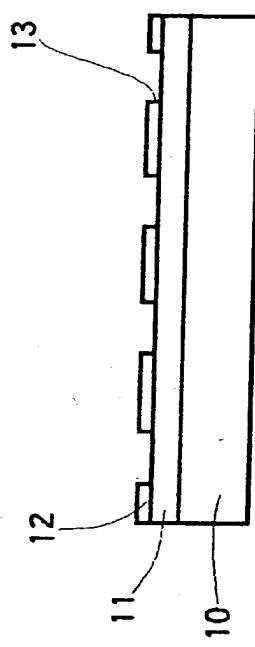


FIG. 1B

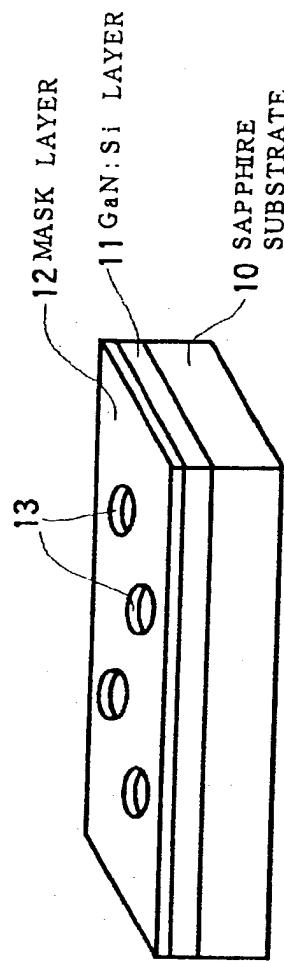


FIG.2B

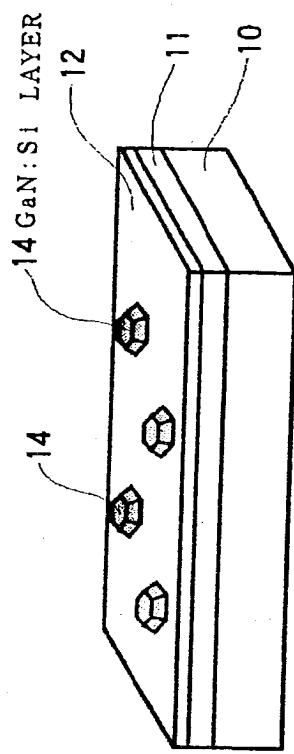
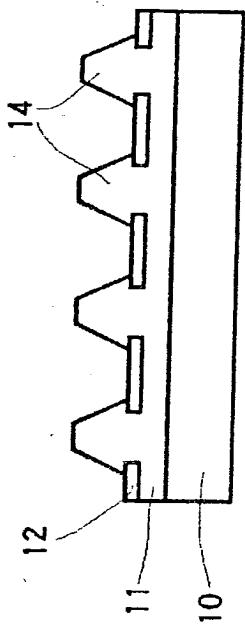


FIG.2A



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FIG.3A

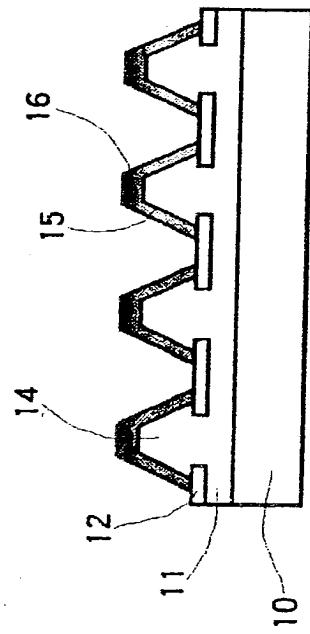


FIG.3B

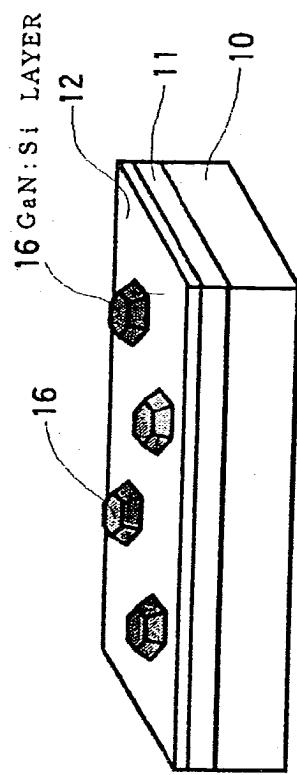


FIG. 4A

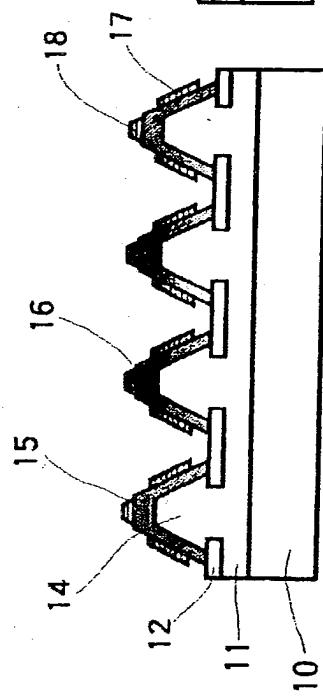
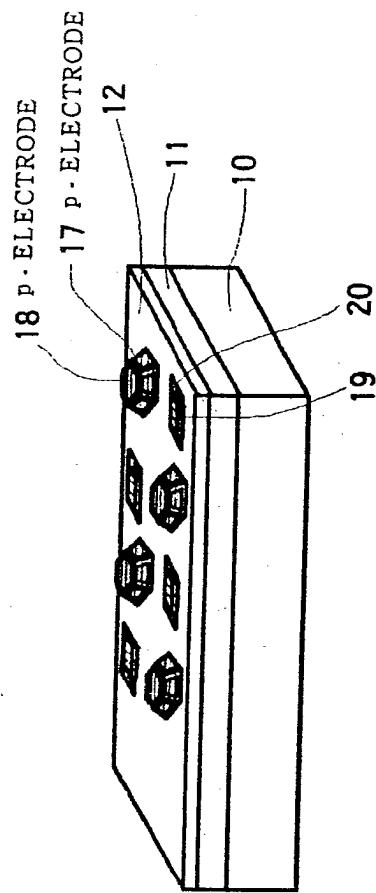


FIG. 4B



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FIG. 5A

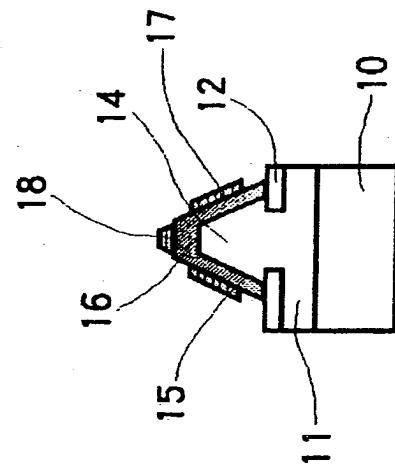


FIG. 5B

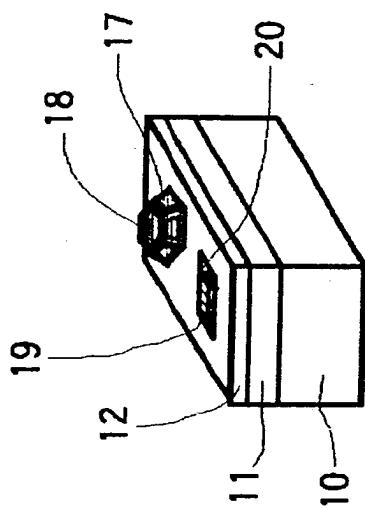


FIG. 6

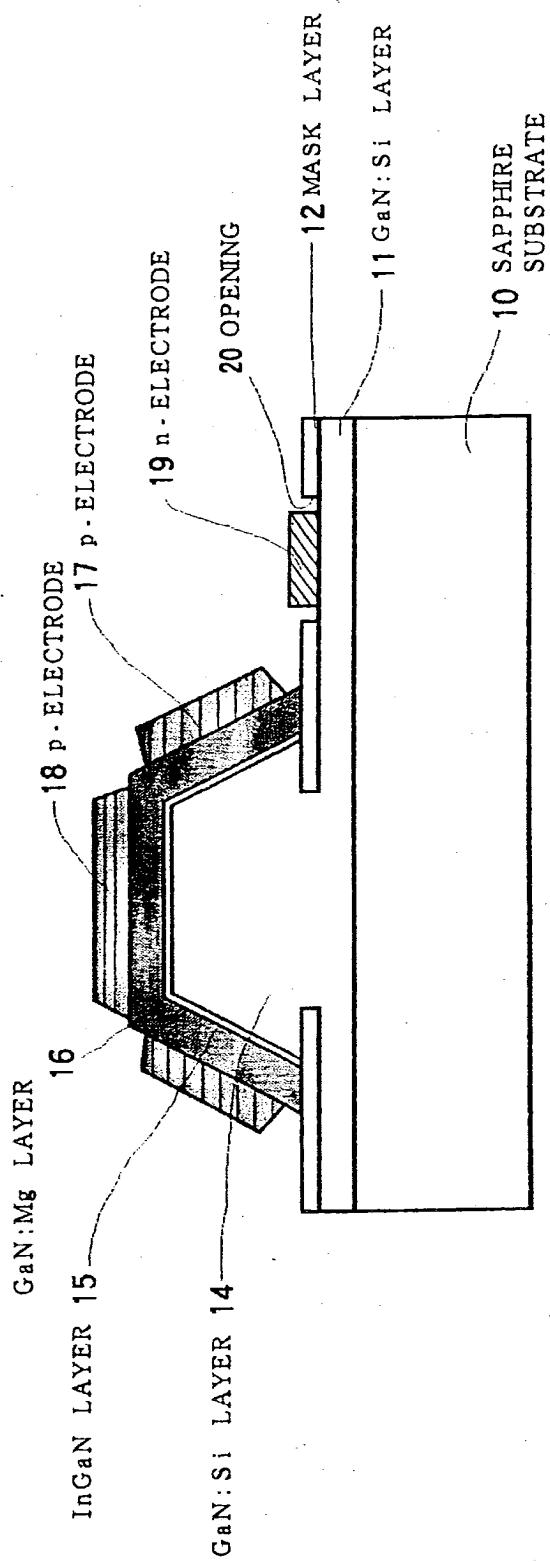


FIG. 7A

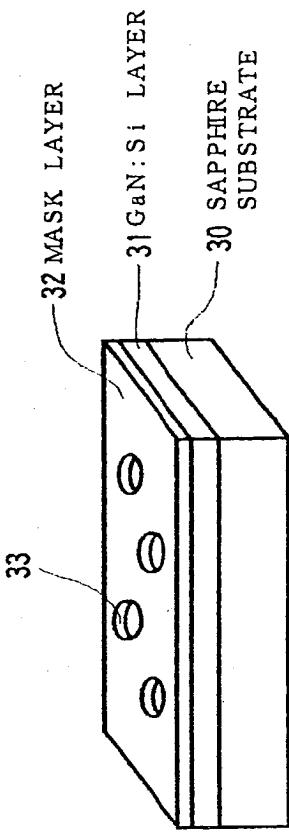
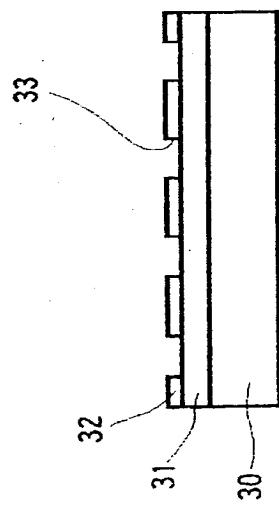


FIG. 8A

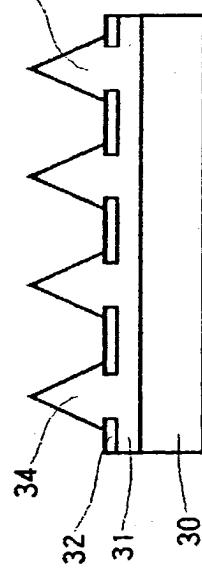
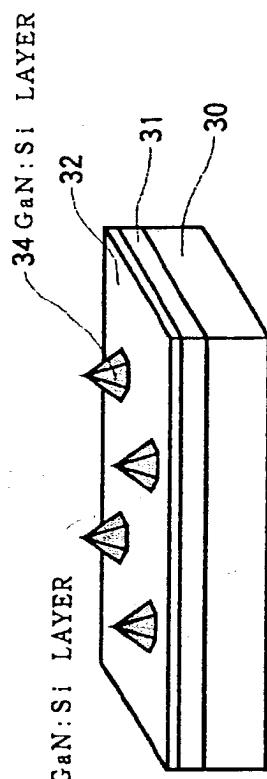


FIG. 8B



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FIG. 9A

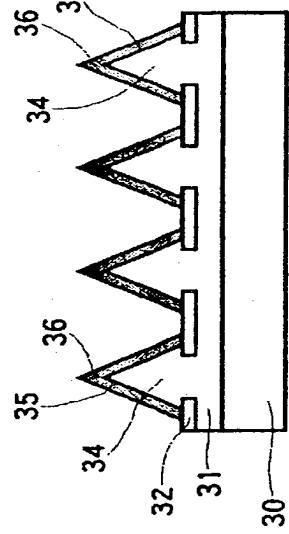
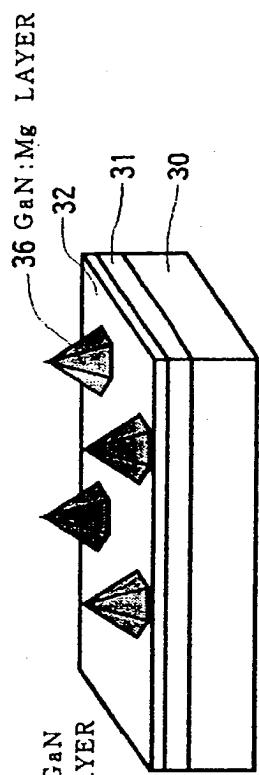
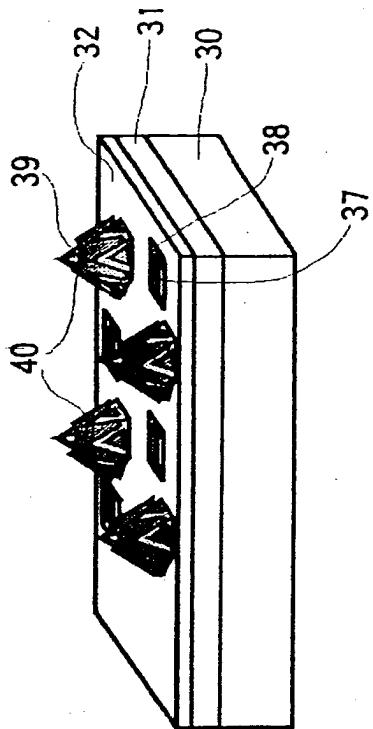
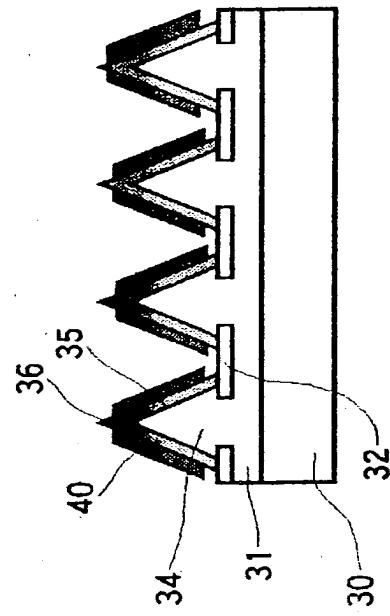


FIG. 9B



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FIG.10A FIG.10B



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FIG. 11A

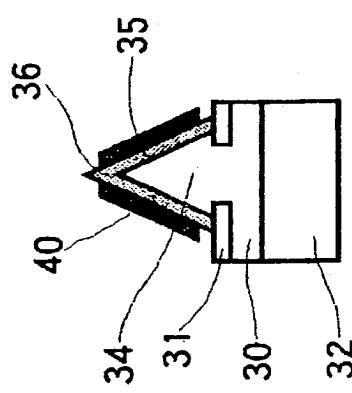
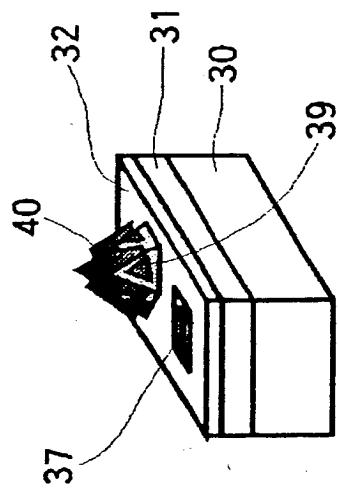


FIG. 11B



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FIG. 12

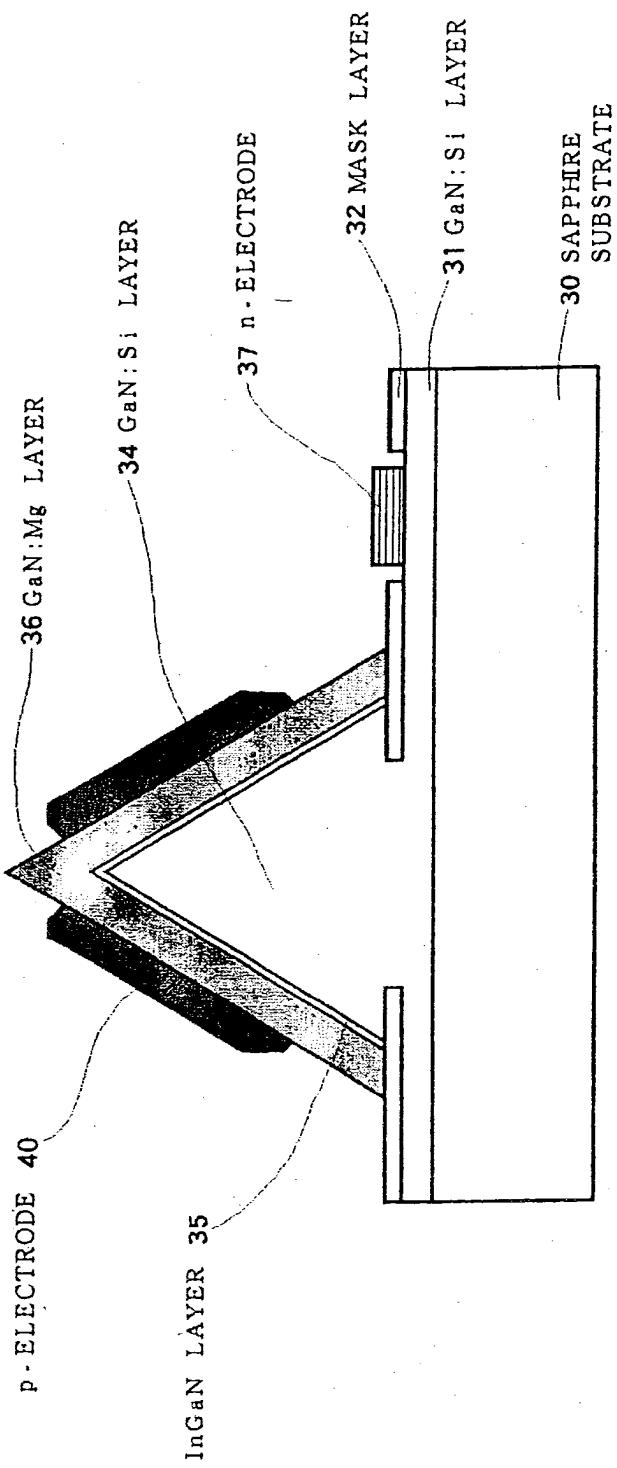


FIG. 13A

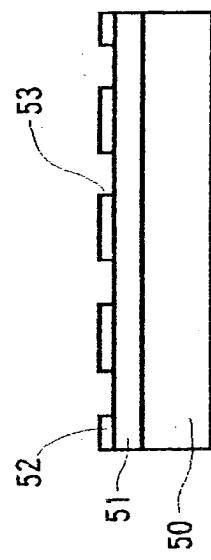


FIG. 13B

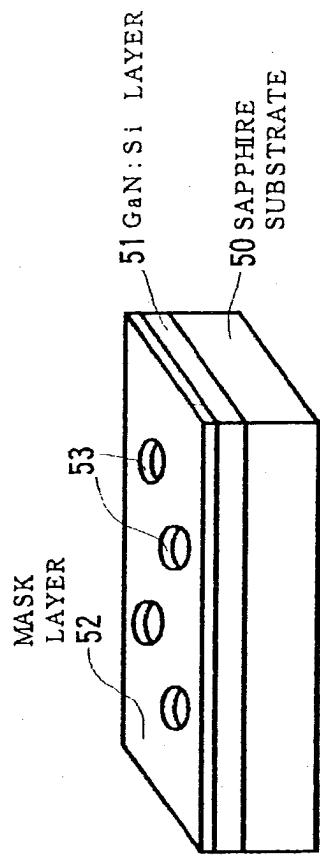


FIG. 14A FIG. 14B

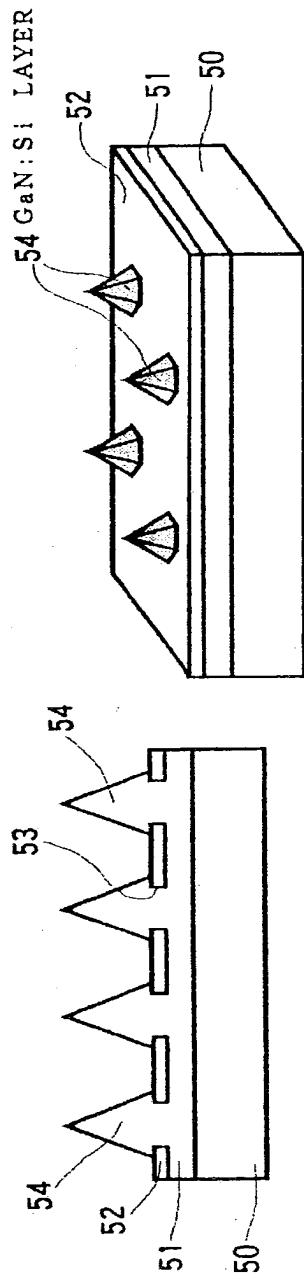
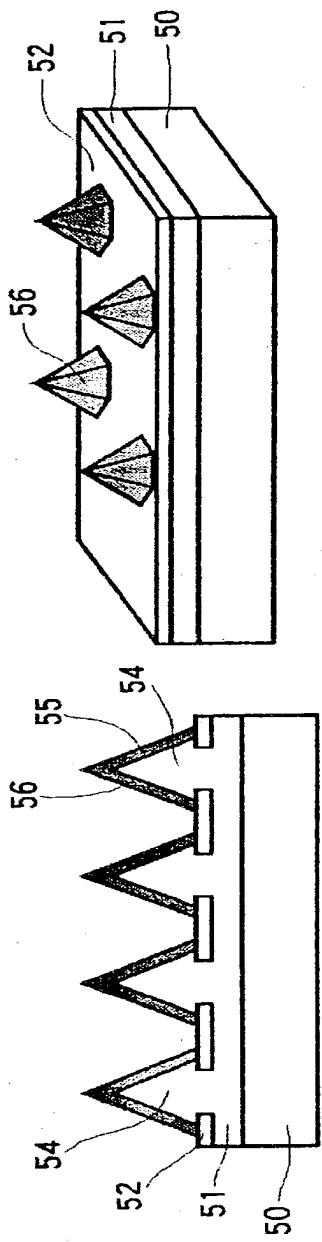


FIG. 15A FIG. 15B



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FIG. 16A

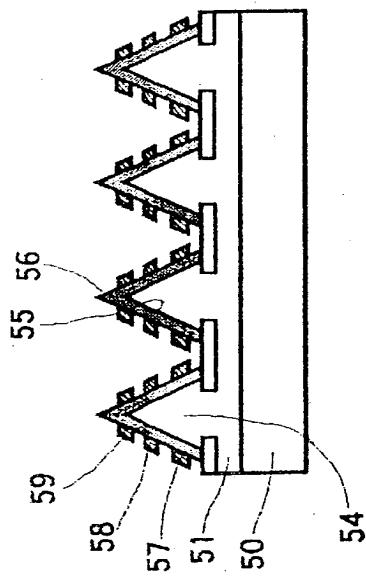


FIG. 16B

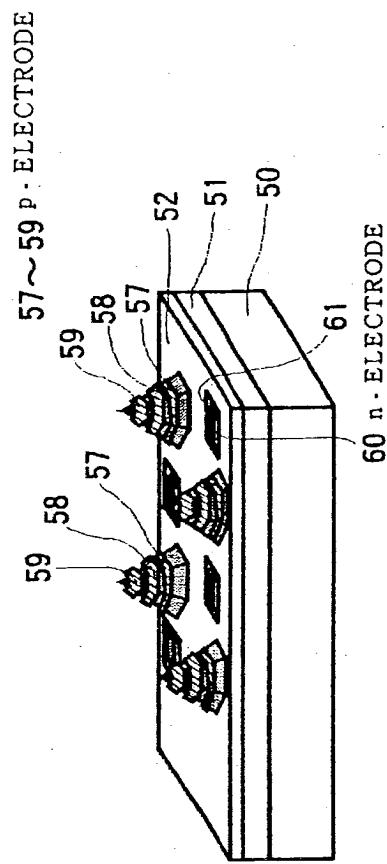


FIG. 17A

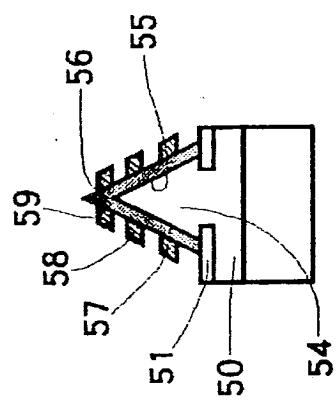
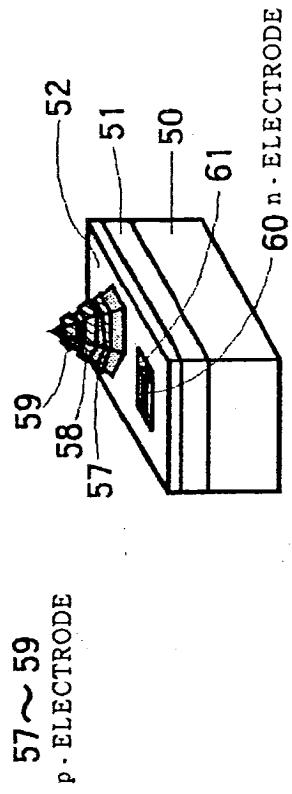
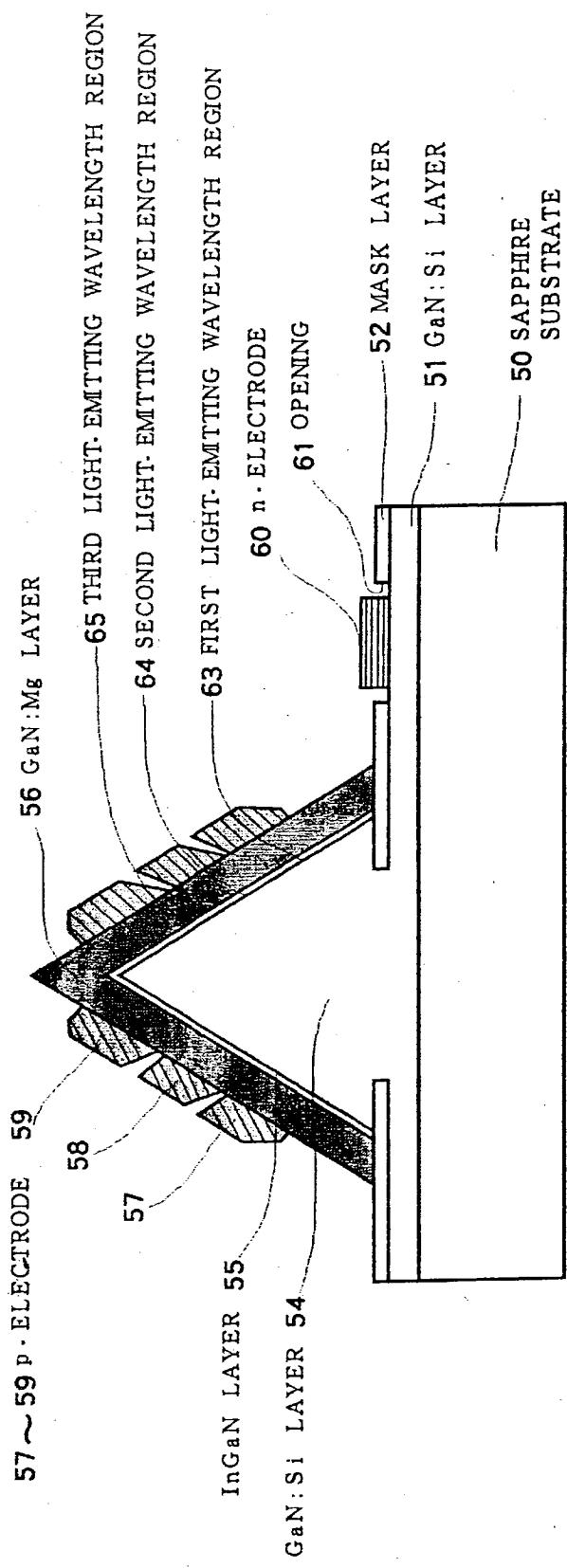


FIG. 17B



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FIG. 18



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FIG. 19A

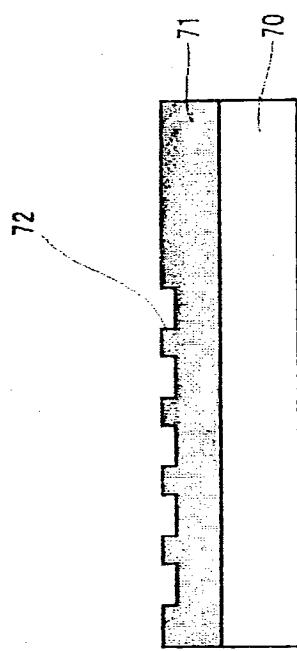


FIG. 19B

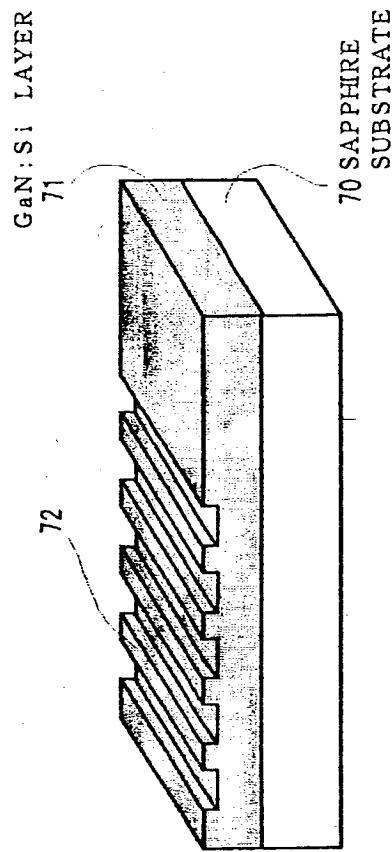


FIG.20A

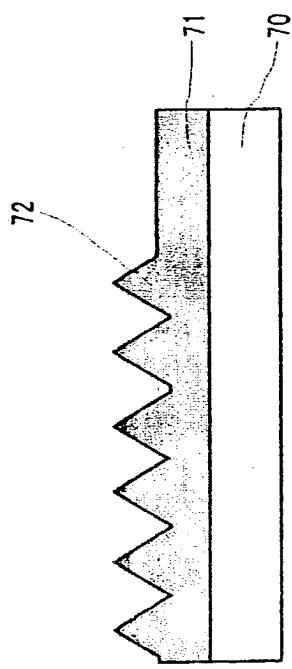
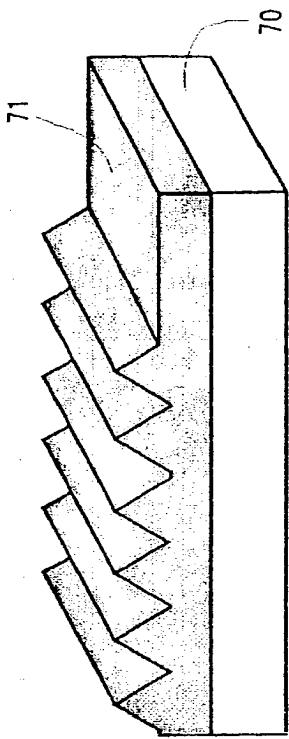


FIG.20B



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FIG.21A

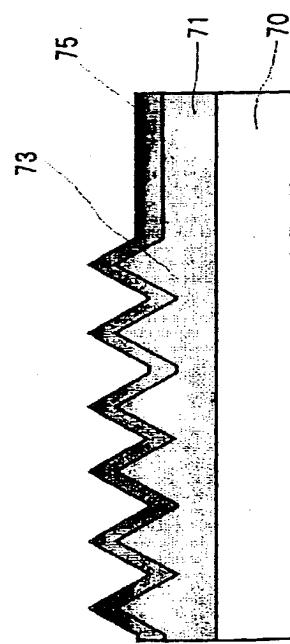
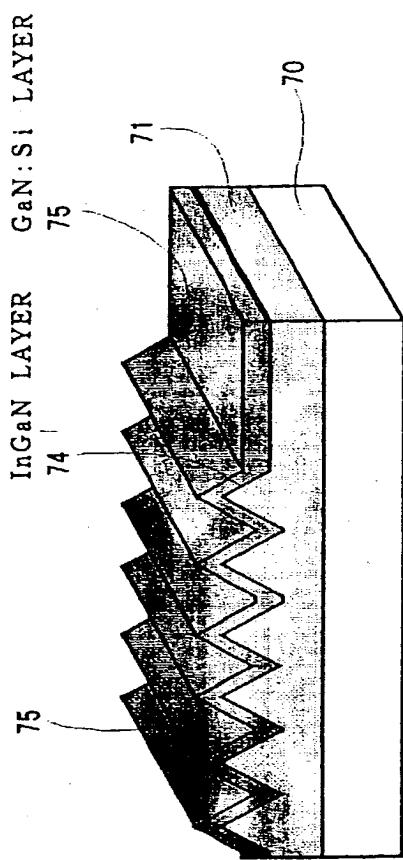


FIG.21B



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FIG. 22A

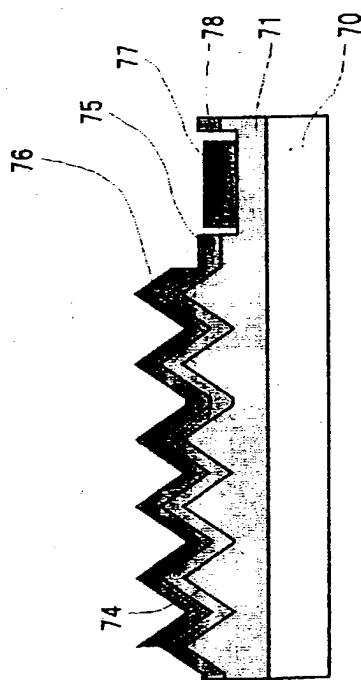
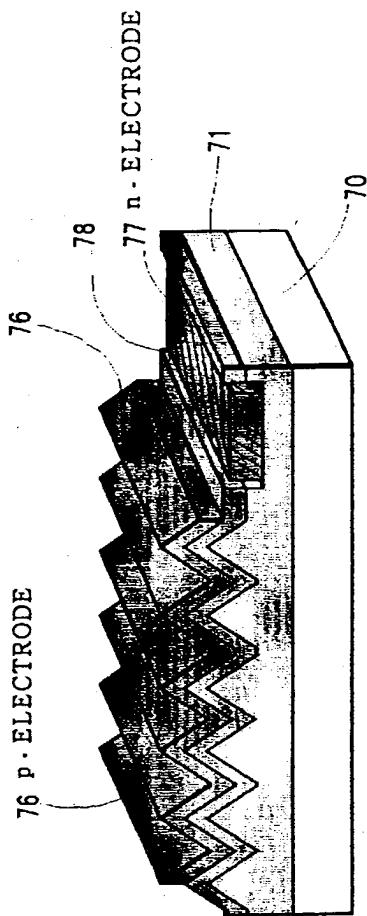


FIG. 22B



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FIG.23

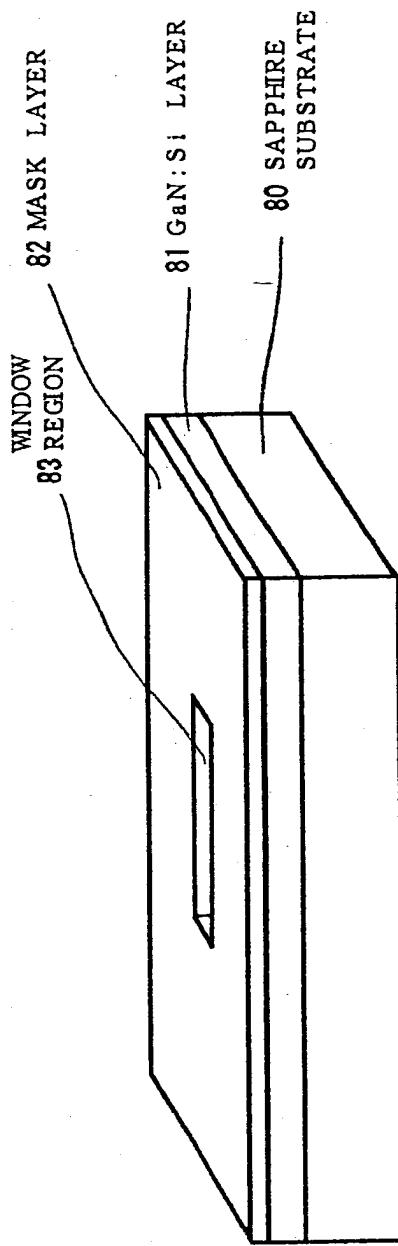


FIG.24

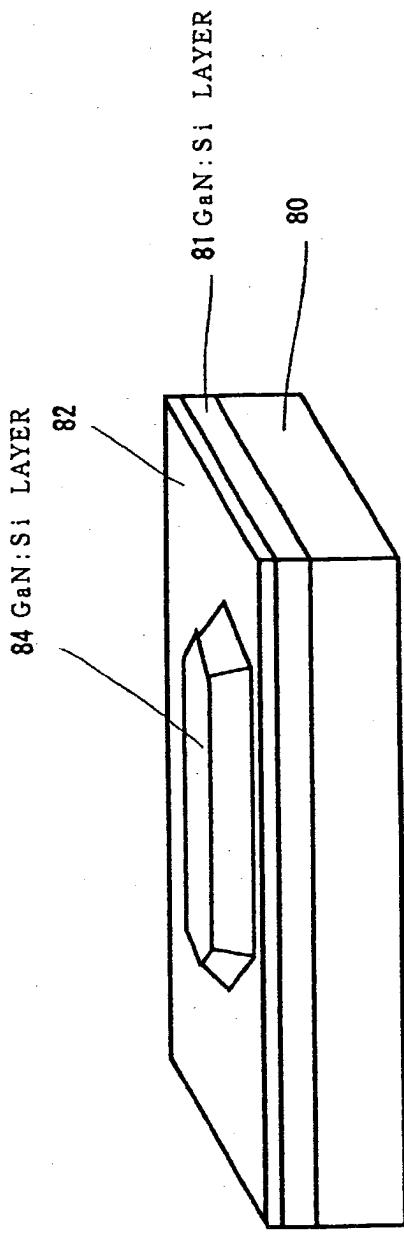


FIG. 25

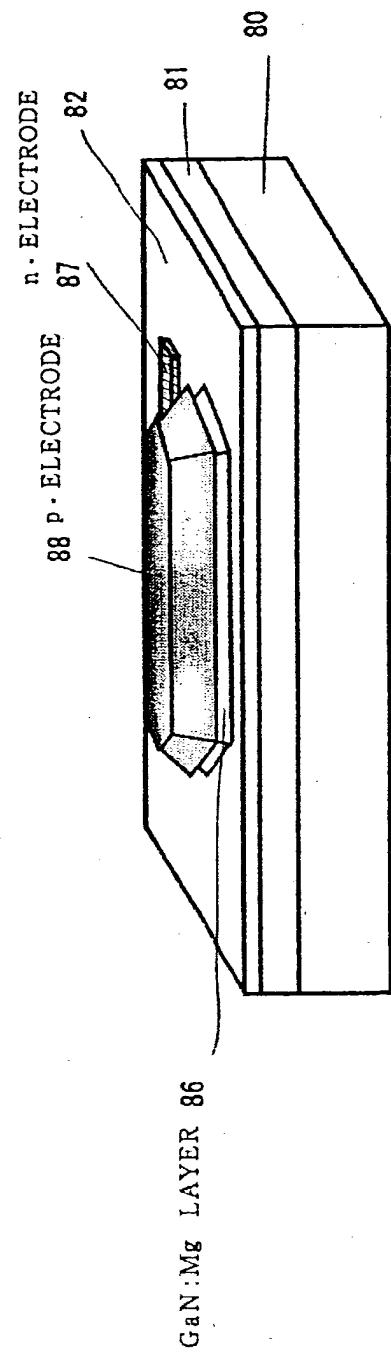


FIG. 26

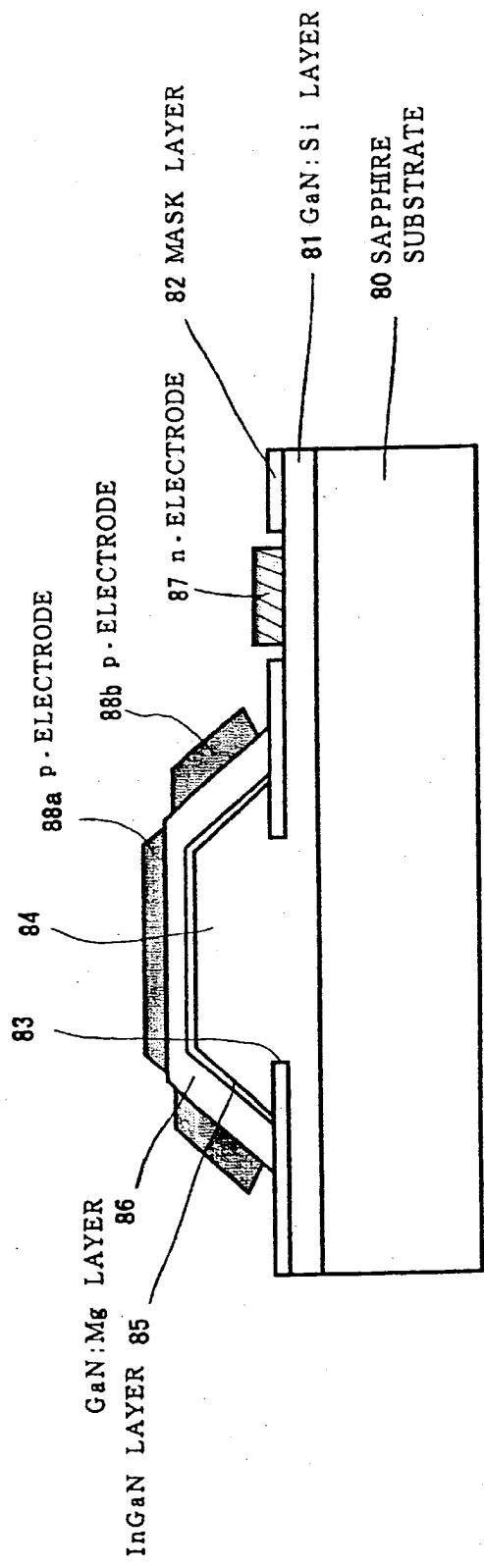
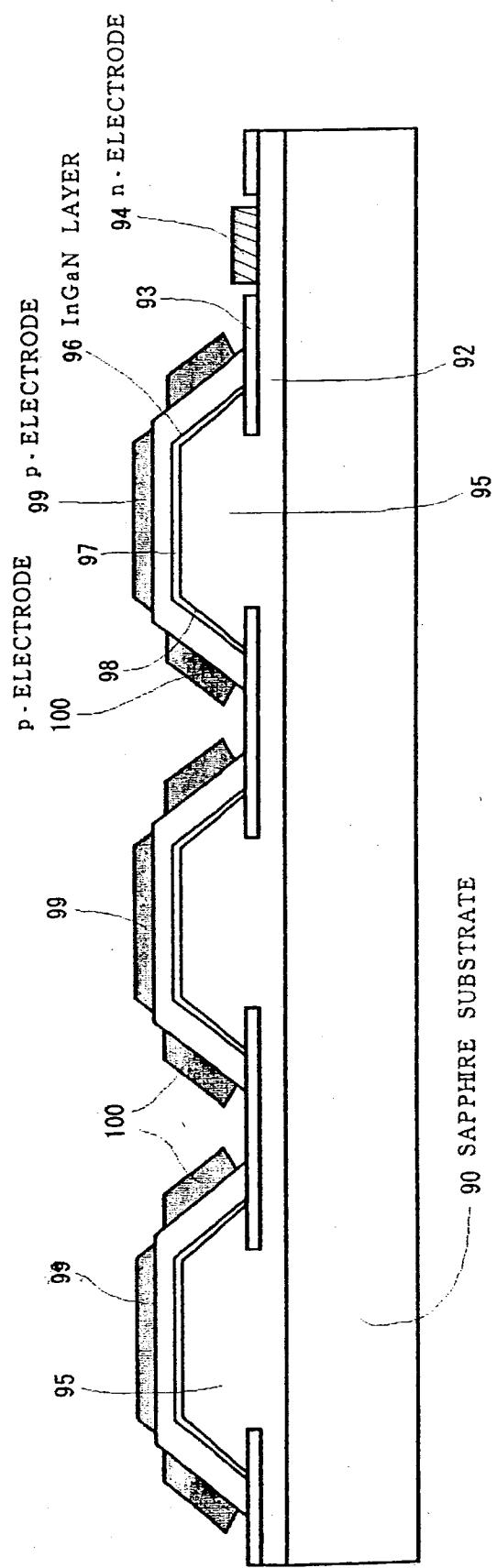


FIG.27



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FIG. 28A

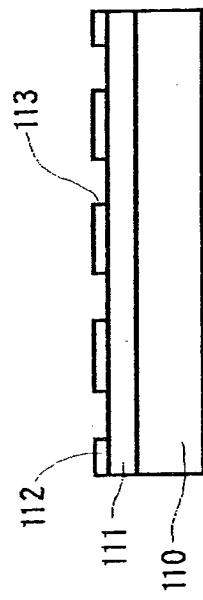


FIG. 28B

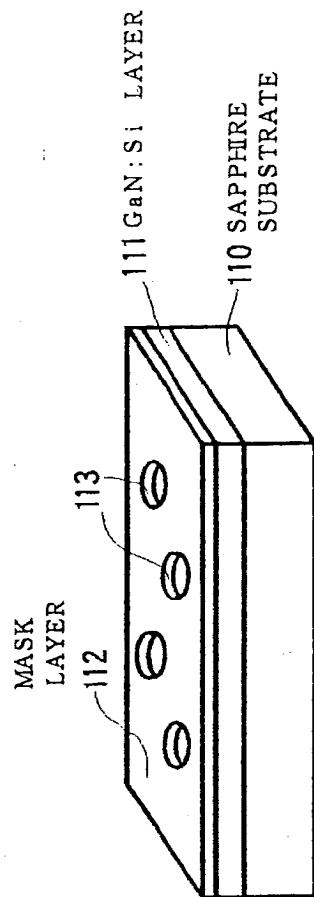
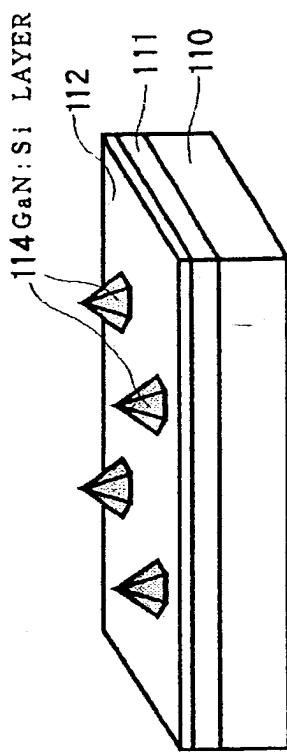
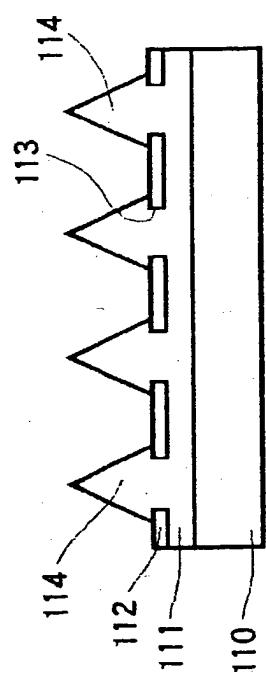


FIG.29A



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FIG. 30A

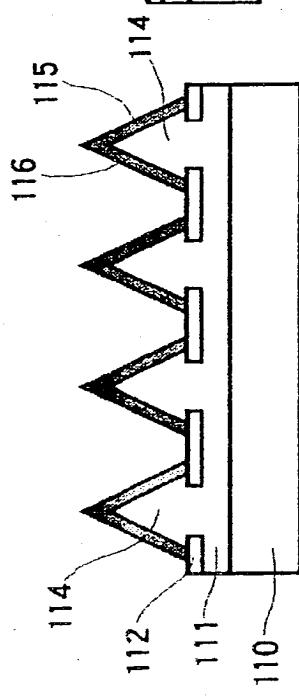


FIG. 30B

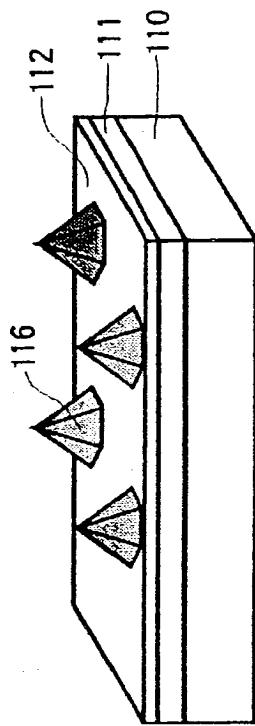


FIG.31A

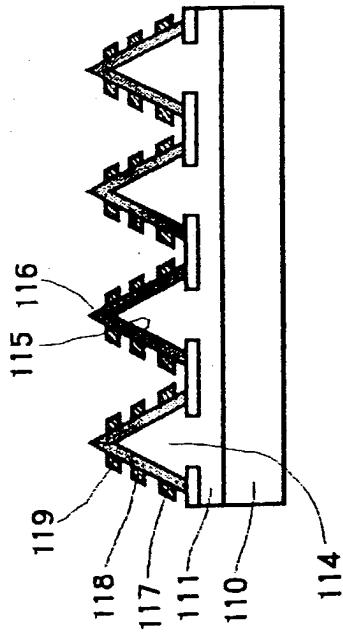


FIG.31B

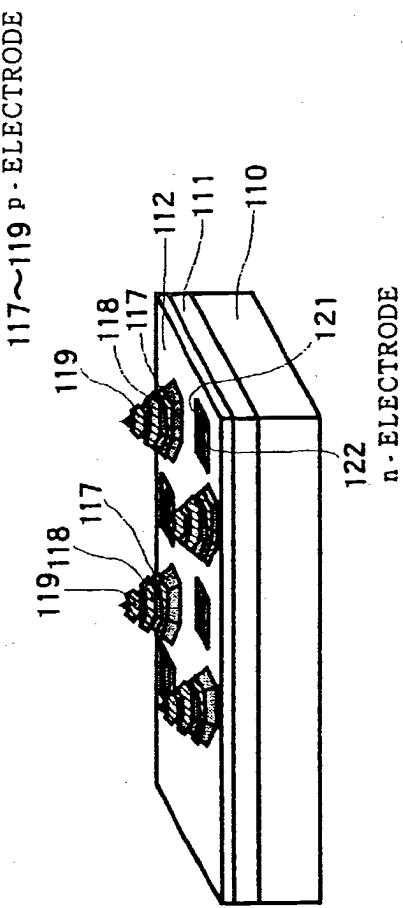


FIG.32A

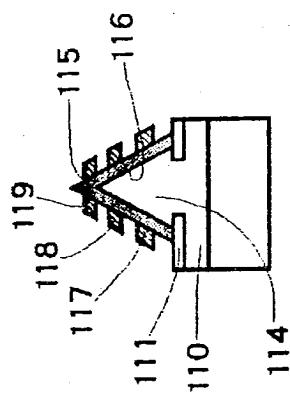
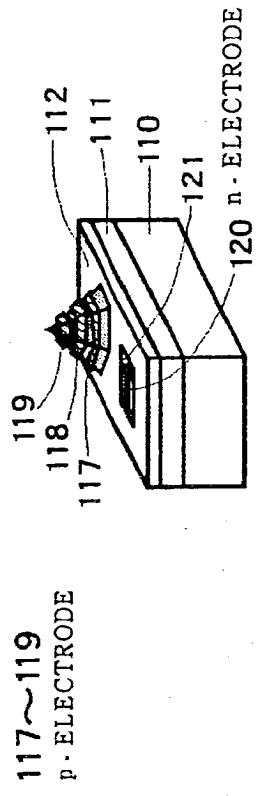
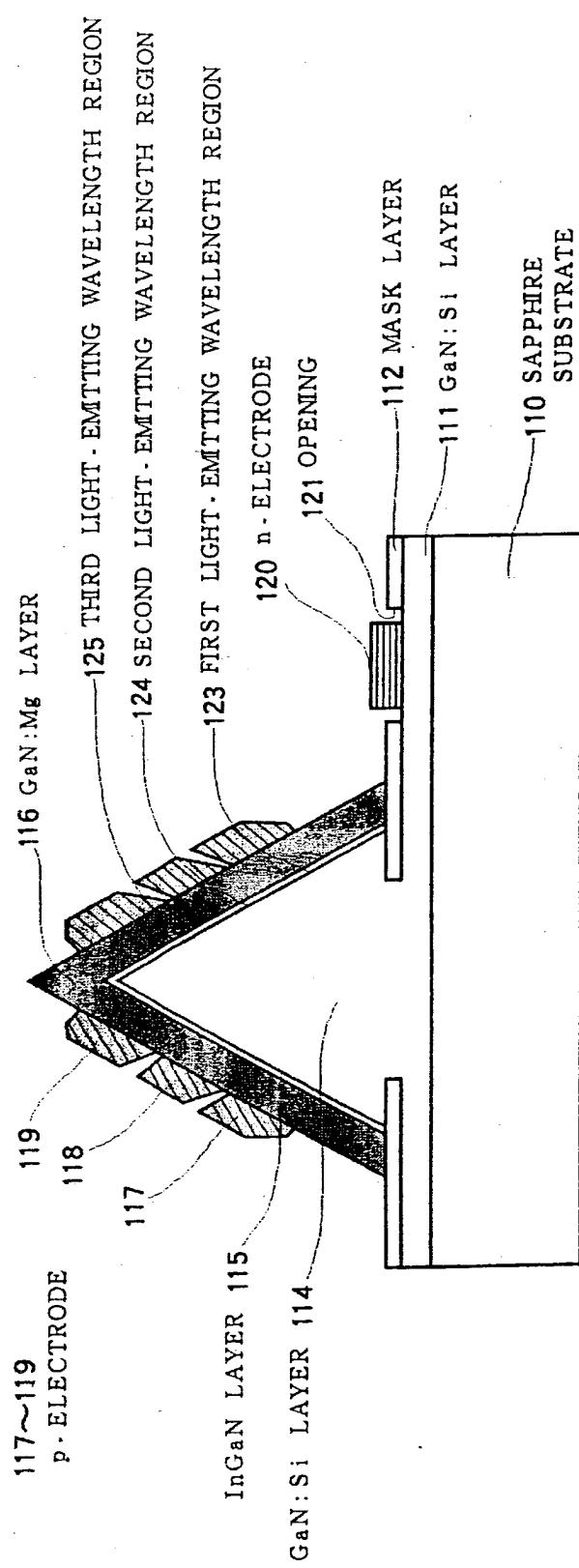


FIG.32B



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FIG.33



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FIG.34A

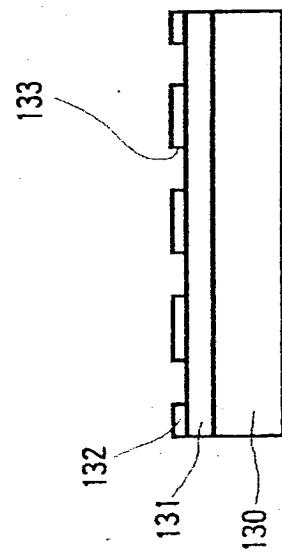
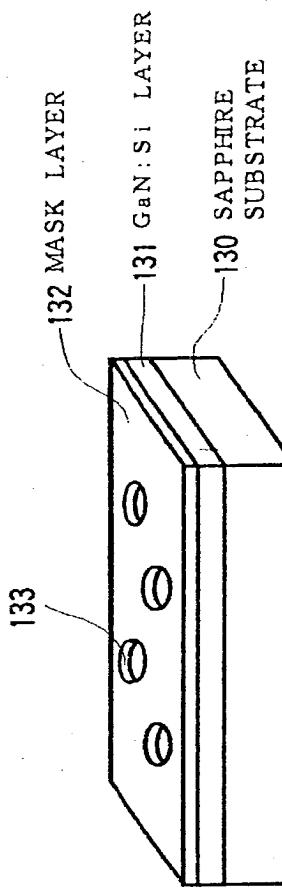


FIG.34B



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FIG. 35A

FIG. 35B

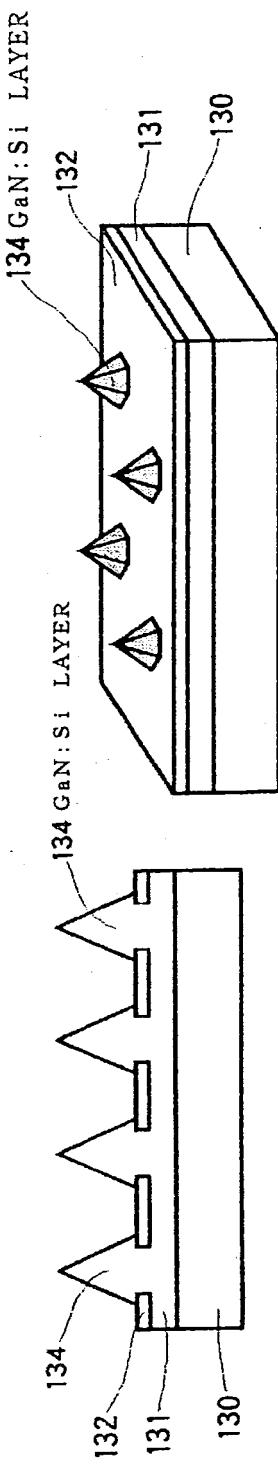


FIG. 36A

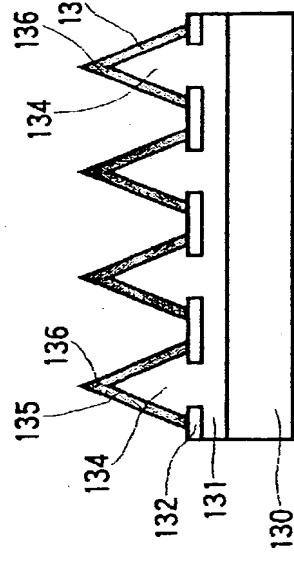
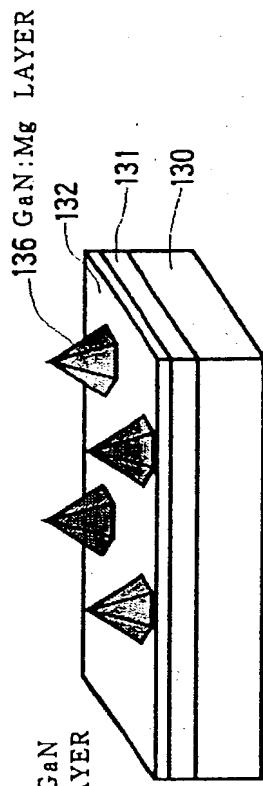


FIG. 36B



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FIG. 37A

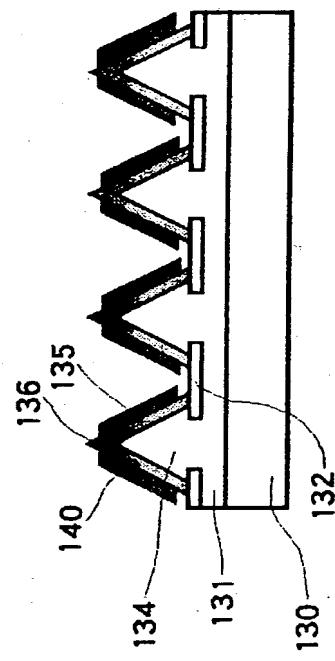
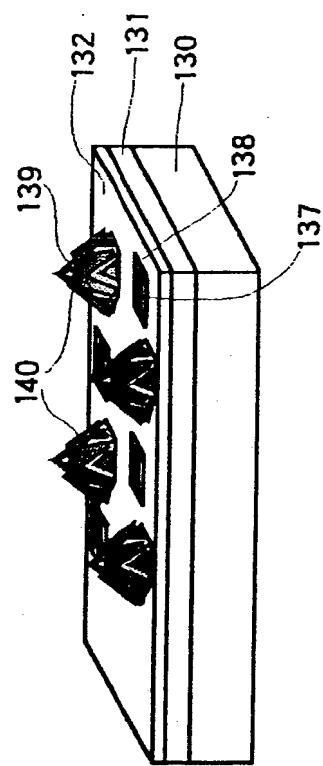


FIG. 37B



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FIG. 38A

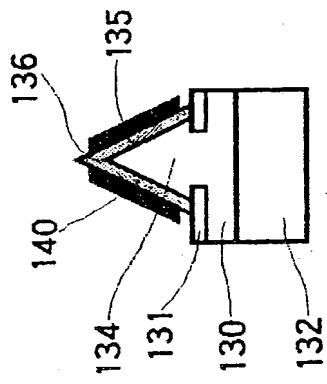
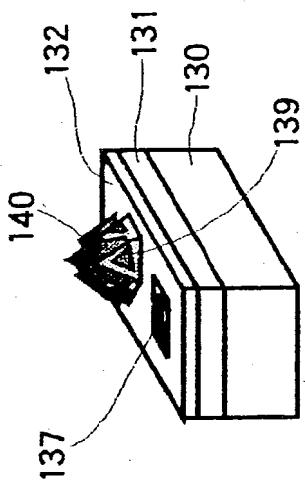


FIG. 38B



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FIG.39

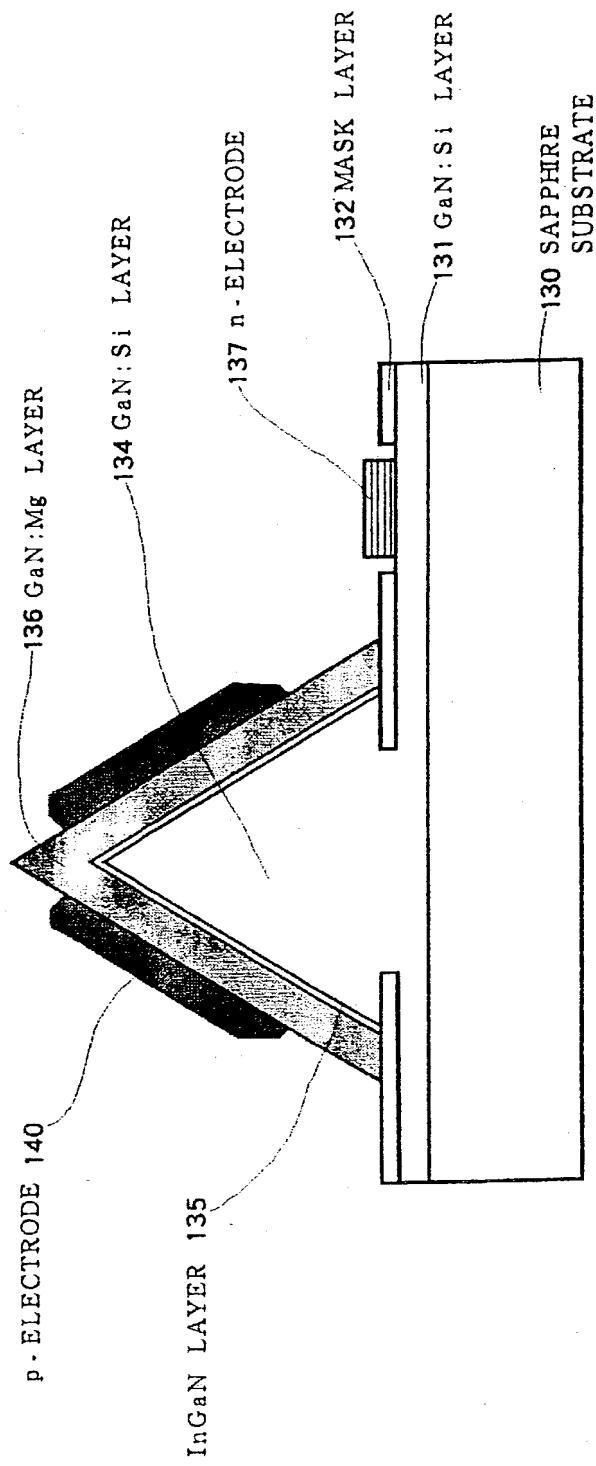


FIG. 40A

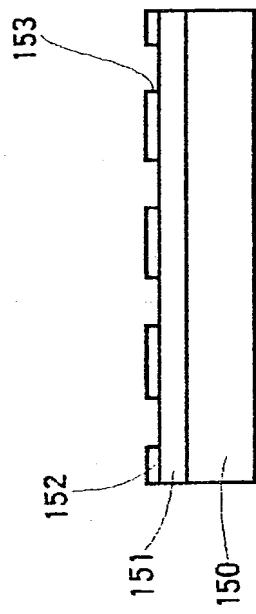


FIG. 40B

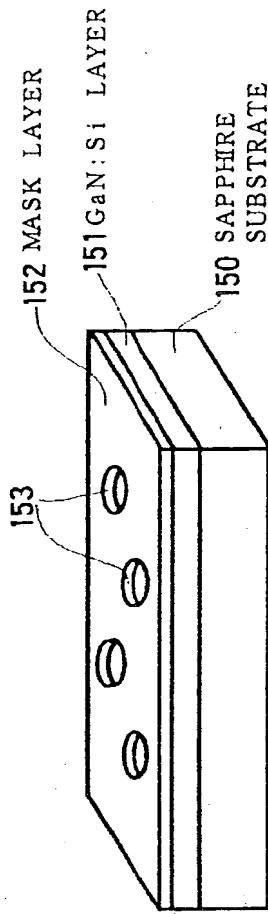


FIG. 41A

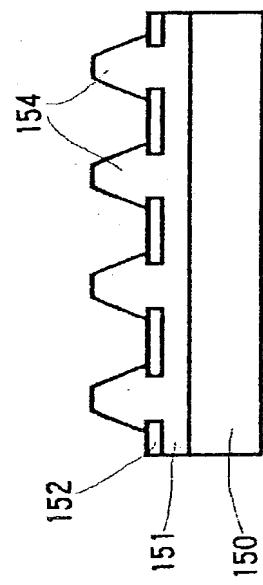


FIG. 41B

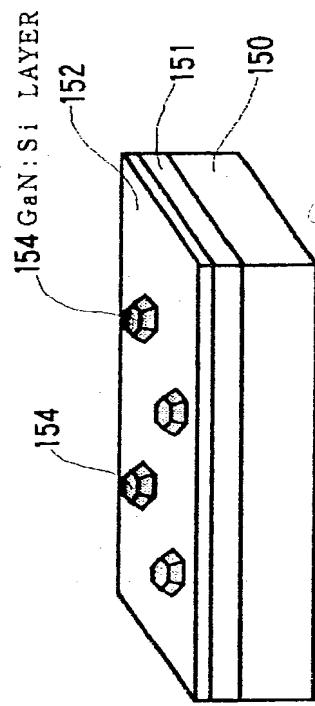


FIG.42A

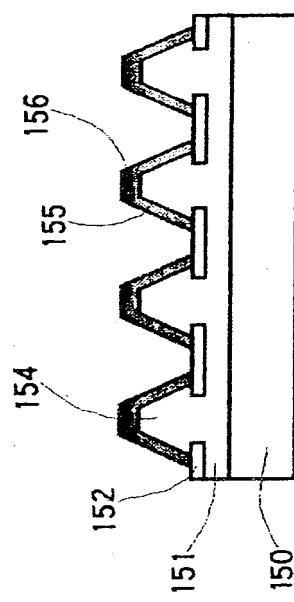
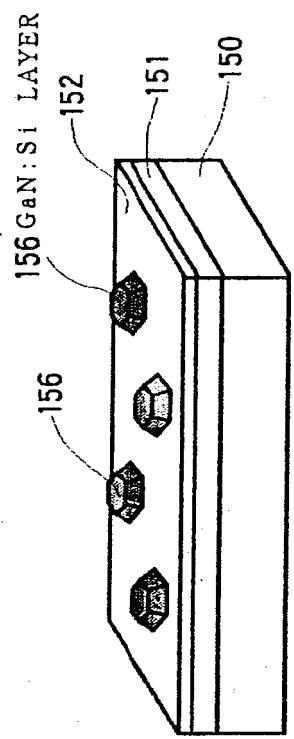


FIG.42B



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FIG.43A

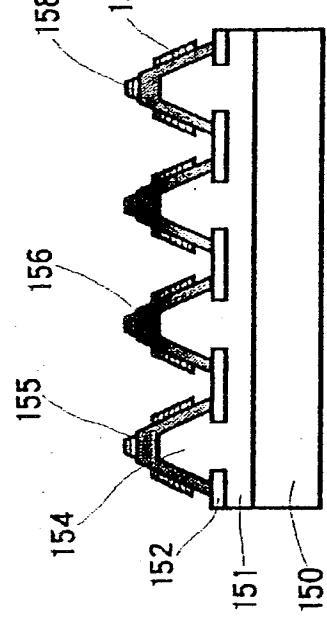
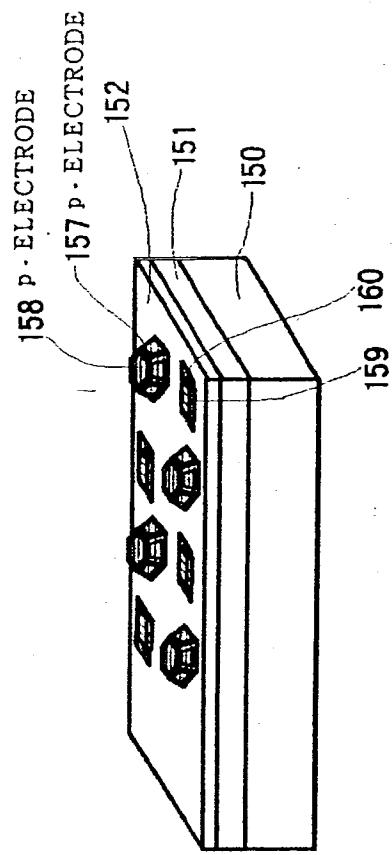


FIG.43B



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FIG. 44A

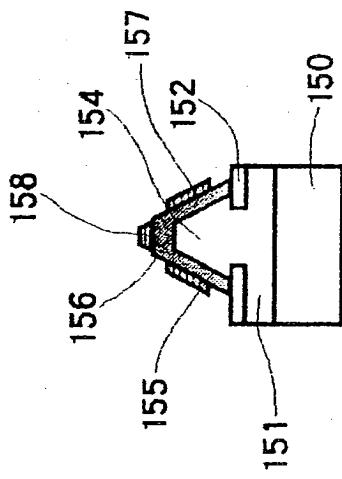
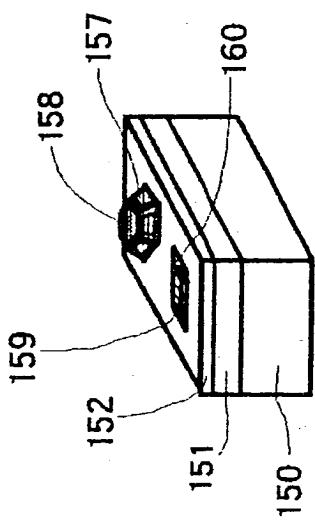


FIG. 44B



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FIG.45

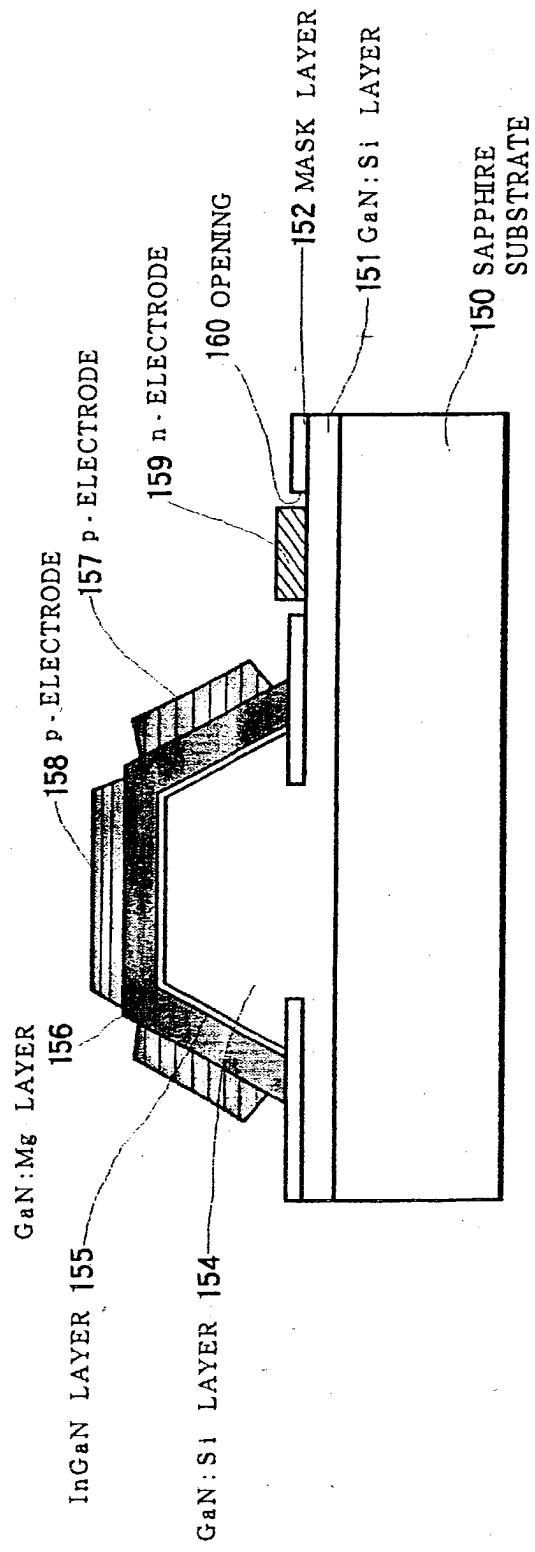


FIG. 46A

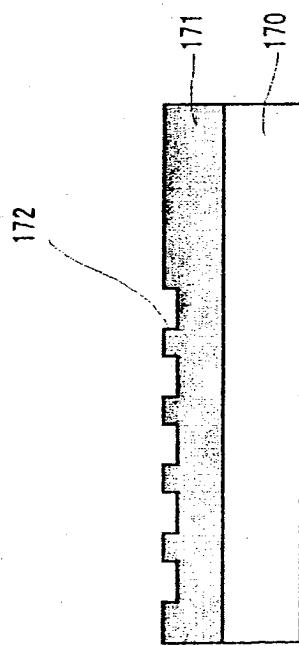
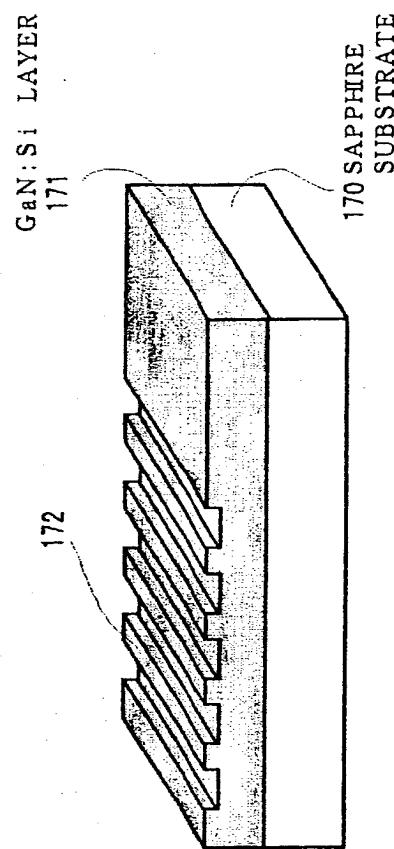


FIG. 46B



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FIG. 47A
FIG. 47B

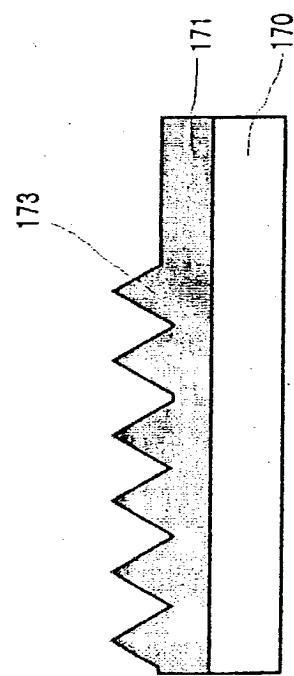


FIG. 47A
FIG. 47B

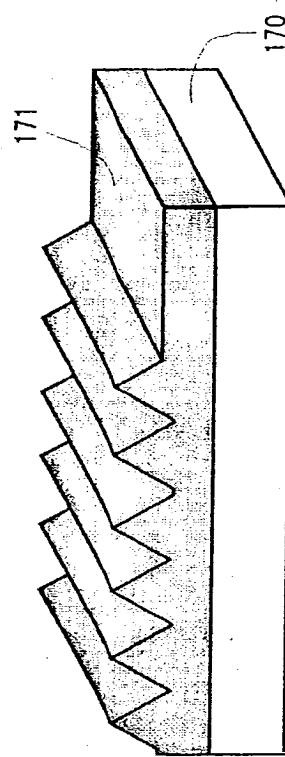


FIG.48A

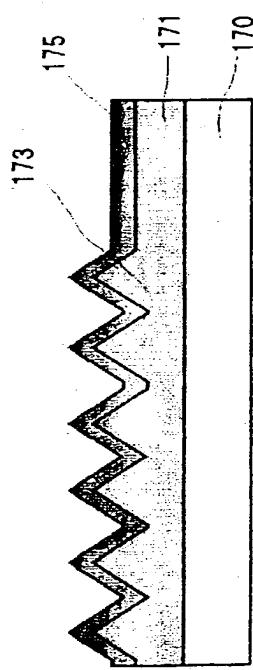
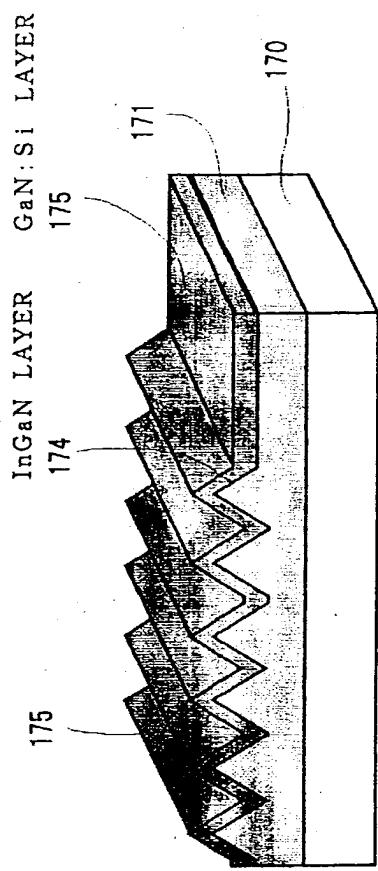


FIG.48B



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FIG. 49A

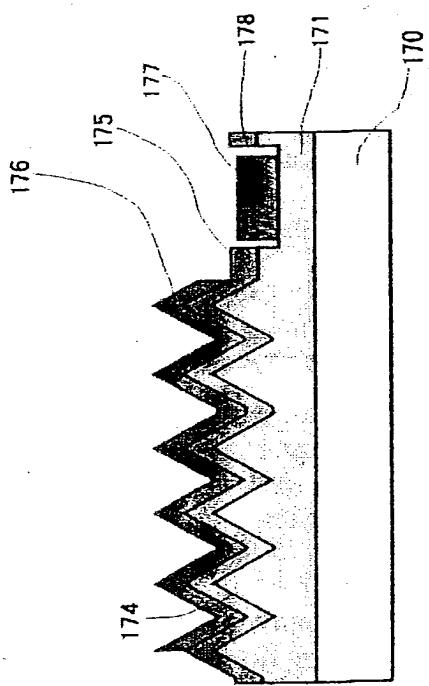


FIG. 49B

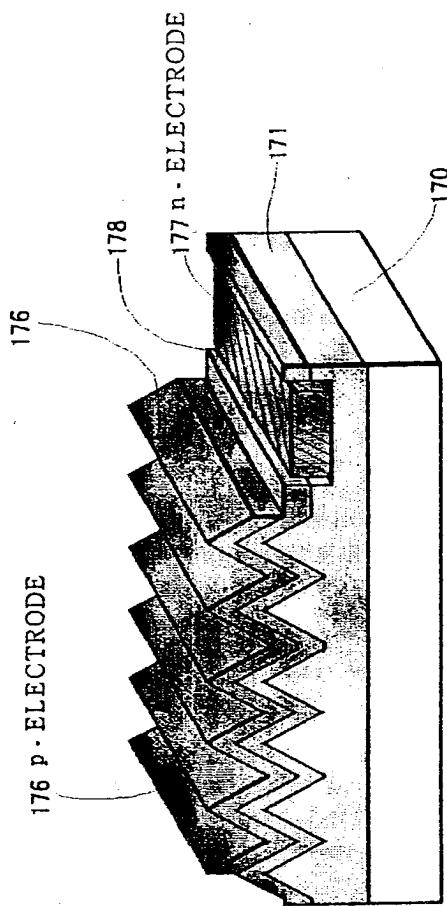


FIG.50

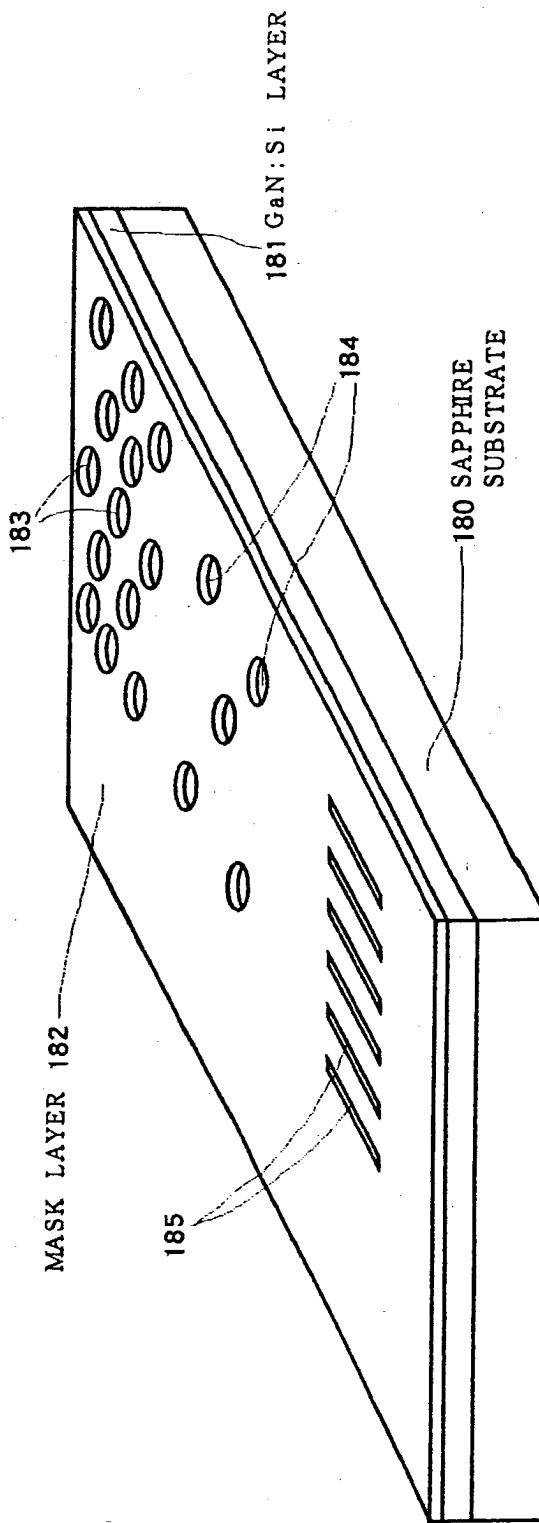


FIG.51

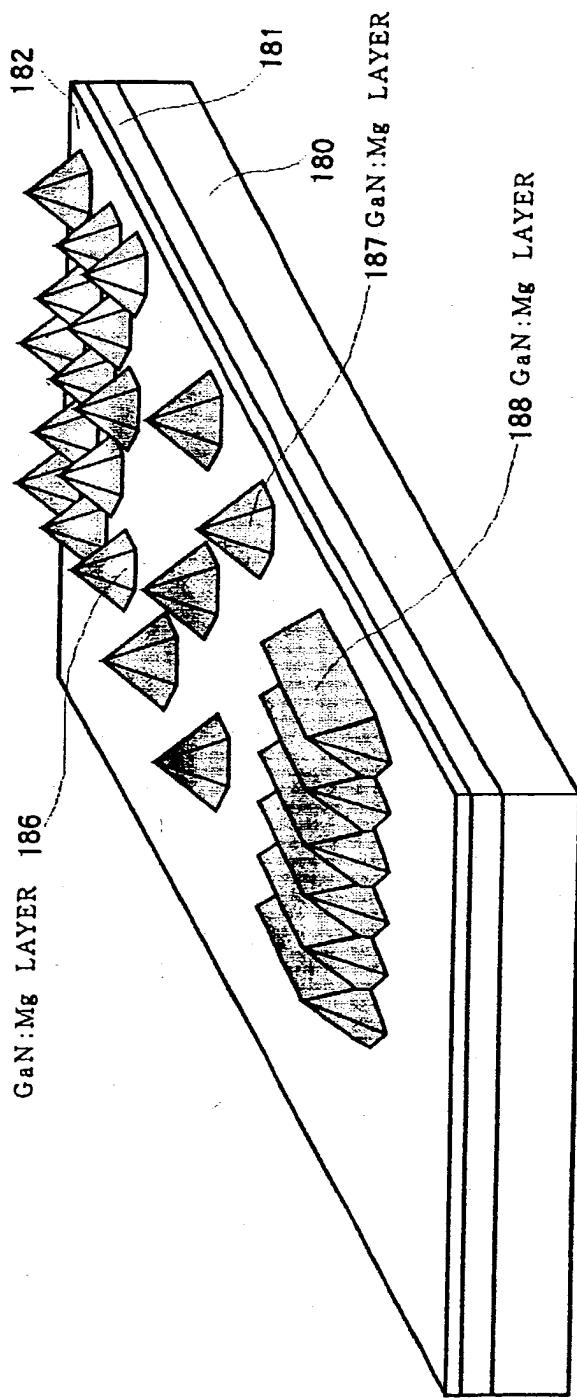
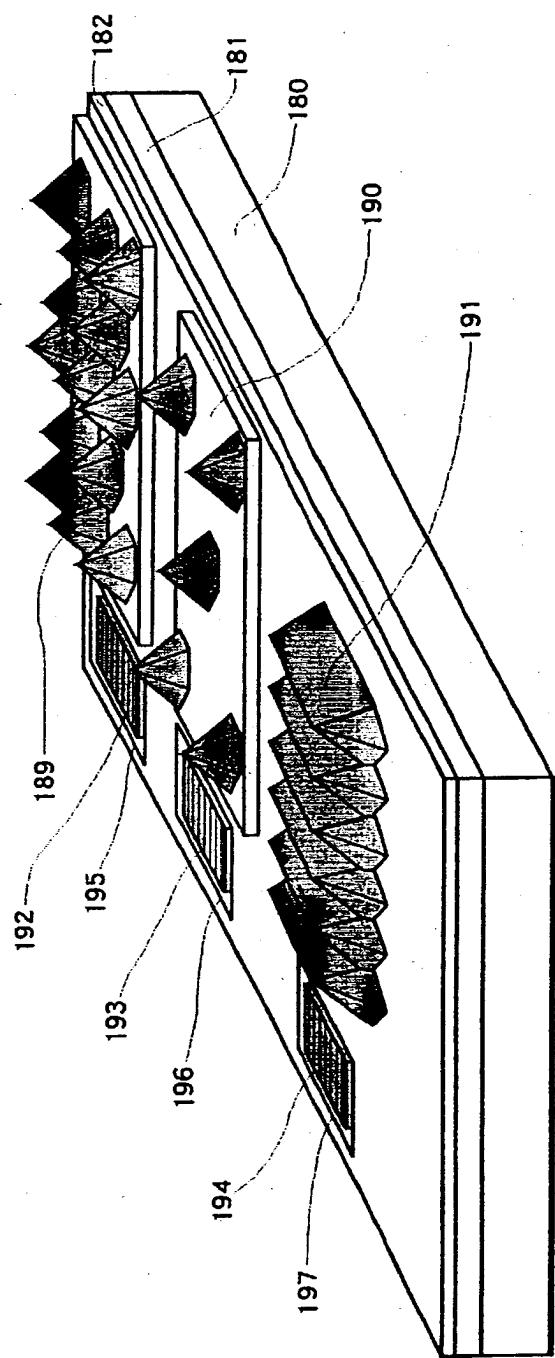
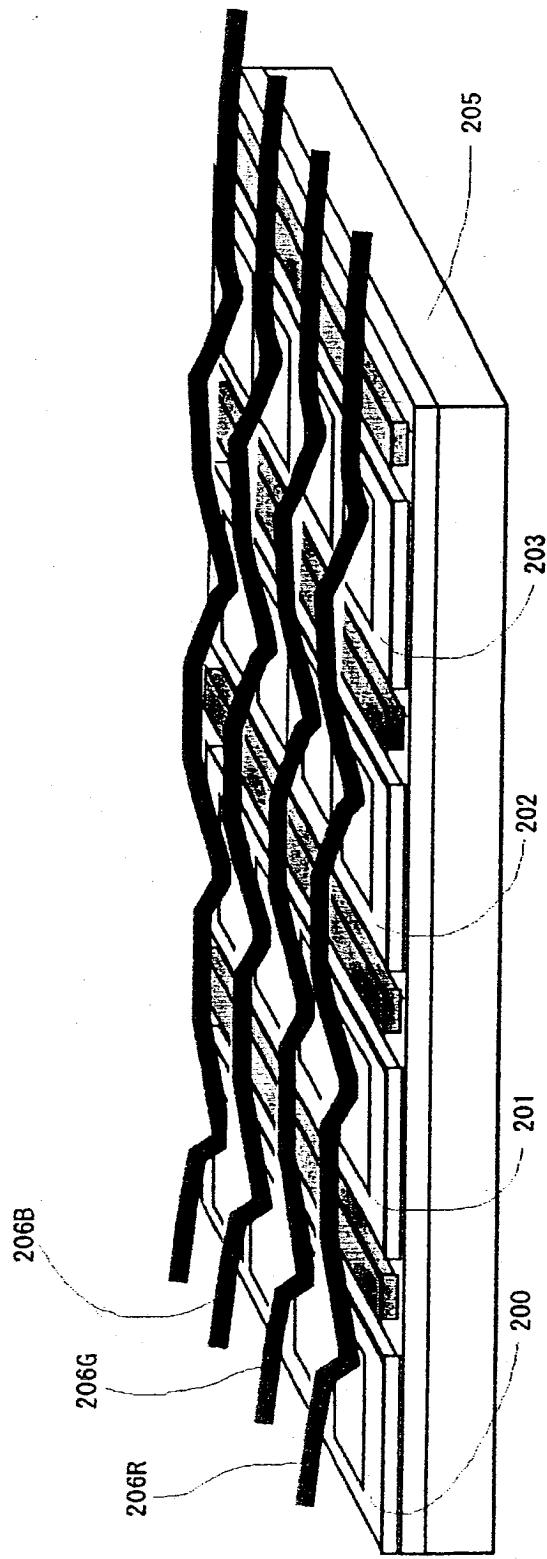


FIG.52



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FIG.53



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Illustration of Reference Numerals

- 10: sapphire substrate**
- 11: Si-doped GaN layer**
- 15: InGaN layer (active layer)**
- 16: Mg-doped GaN layer**
- 17: p-electrode**
- 19: n-electrode**
- 111: Si-doped GaN layer.**
- 200: semiconductor light-emitting device**